SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R-MAY 1992-REVISED NOVEMBER 2006

FEATURES

- Members of the Texas Instruments Widebus™ Family
- State-of-the-Art Advanced BiCMOS
 Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

SN54LVTH16245A... WD PACKAGE SN74LVTH16245A... DGG, DGV, OR DL PACKAGE (TOP VIEW)

1				
1DIR	1	\cup_{4}	8	1 OE
1B1 🛚	2	4	7	1A1
1B2	3	4	6[]	1A2
GND [4	4	5[]	GND
1B3 🛚	5	4	4[]	1A3
1B4 🛚	6	4	з[]	1A4
v _{cc} [7	4	2	V_{CC}
1B5 🛚	8	4	1[1A5
1B6	9	4	0[]	1A6
GND	10	3	9[GND
1B7	11	3	8[]	1A7
1B8	12	3	7[]	1A8
2B1	13	3	6	2A1
2B2	14	3	5[]	2A2
GND [15	3	4[]	GND
2B3 🛚	16	3	з[]	2A3
2B4 🛚	17	3	2	2A4
v _{cc} [18	3	1	V_{CC}
2B5 🛚	19	3	0	2A5
2B6 🛚	20	2	9	2A6
GND [21	2	8	GND
2B7 [22	2	7	2A7
2B8 🛚	23	2	6	2A8
2DIR	24	2	5	2 OE

DESCRIPTION/ORDERING INFORMATION

The 'LVTH16245A devices are 16-bit (dual-octal) noninverting 3-state transceivers designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The devices are designed for asynchronous communication between two data buses. The logic levels of the direction-control (DIR) input and the output-enable (\overline{OE}) input activate either the B-port outputs or the A-port outputs or place both output ports into the high-impedance mode. The device transmits data from the A bus to the B bus when the B-port outputs are activated, and from the B bus to the A bus when the A-port outputs are activated. The input circuitry on both A and B ports is always active and must have a logic HIGH or LOW level applied to prevent excess I_{CC} and I_{CCZ} .

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using $I_{\rm off}$ and power-up 3-state. The $I_{\rm off}$ circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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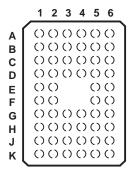


ORDERING INFORMATION

T _A	PACKAGI	E (1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	FBGA – GRD	Reel of 1000	SN74LVTH16245AGRDR	- LL245A
	FBGA – ZRD (Pb-free)	Reel of 1000	SN74LVTH16245AZRDR	LL243A
		Tube of 25	74LVTH16245ADL	
	SSOP – DL	Tube of 25	74LVTH16245ADLG4	- LVTH16245A
	330P - DL	Reel of 1000	74LVTH16245ADLR	LVINI0245A
		Reel of 1000	74LVTH16245ADLRG4	
–40°C to 85°C			SN74LVTH16245ADGGR	
	TSSOP - DGG	Reel of 2000	74LVTH16245ADGGRE4	LVTH16245A
			74LVTH16245ADGGRG4	
	TVSOP – DGV	Reel of 2000	SN74LVTH16245ADGVR	- LL245A
	TVSOF - DGV	Reel of 2000	74LVTH16245ADGVRE4	LL243A
	VFBGA – GQL	Reel of 1000	SN74LVTH16245AGQLR	- LL245A
	VFBGA – ZQL (Pb-free)	Veel of 1000	74LVTH16245AZQLR	LL243A
-55°C to 125°C	CFP – WD	Tube	SNJ54LVTH16245AWD	SNJ54LVTH16245AWD

⁽¹⁾ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

GQL OR ZQL PACKAGE (TOP VIEW)



TERMINAL ASSIGNMENTS⁽¹⁾ (56-Ball GQL/ZQL Package)

	1	2	3	4	5	6
Α	1DIR	NC	NC	NC	NC	1 OE
В	1B2	1B1	GND	GND	1A1	1A2
С	1B4	1B3	V _{CC}	V _{CC}	1A3	1A4
D	1B6	1B5	GND	GND	1A5	1A6
Е	1B8	1B7			1A7	1A8
F	2B1	2B2			2A2	2A1
G	2B3	2B4	GND	GND	2A4	2A3
Н	2B5	2B6	V _{CC}	V _{CC}	2A6	2A5
J	2B7	2B8	GND	GND	2A8	2A7
K	2DIR	NC	NC	NC	NC	2 OE

(1) NC - No internal connection

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SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R-MAY 1992-REVISED NOVEMBER 2006

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TERMINAL ASSIGNMENTS⁽¹⁾ (54-Ball GRD/ZRD Package)

	1	2	3	4	5	6
Α	1B1	NC	1DIR	1 OE	NC	1A1
В	1B3	1B2	NC	NC	1A2	1A3
С	1B5	1B4	V _{CC}	V_{CC}	1A4	1A5
D	1B7	1B6	GND	GND	1A6	1A7
E	2B1	1B8	GND	GND	1A8	2A1
F	2B3	2B2	GND	GND	2A2	2A3
G	2B5	2B4	V _{CC}	V_{CC}	2A4	2A5
Н	2B7	2B6	NC	NC	2A6	2A7
J	2B8	NC	2DIR	2 0E	NC	2A8

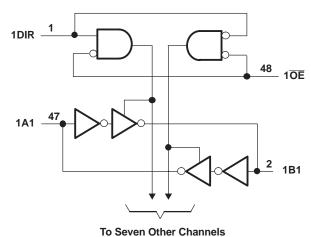
(1) NC - No internal connection

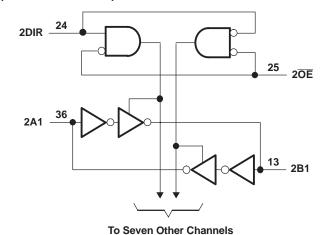
FUNCTION TABLE⁽¹⁾ (EACH 8-BIT SECTION)

	TROL UTS	OUTPUT	CIRCUITS	OPERATION
ŌĒ	OE DIR A POF		B PORT	
L	L	Enabled	Hi-Z	B data to A bus
L	Н	Hi-Z	Enabled	A data to B bus
Н	Χ	Hi-Z	Hi-Z	Isolation

(1) Input circuits of the data I/Os always are active.

LOGIC DIAGRAM (POSITIVE LOGIC)





SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R-MAY 1992-REVISED NOVEMBER 2006



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_{I}	Input voltage range (2)		-0.5	7	V
Vo	Voltage range applied to any output in the high-ir	-0.5	7	V	
Vo	Voltage range applied to any output in the high s	-0.5	V _{CC} + 0.5	V	
	Current into any autout in the law state	SN54LVTH16245A		96	A
I _O	Current into any output in the low state	SN74LVTH16245A		128	mA
	Compart into any autout in the high state (3)	SN54LVTH16245A		48	mA
I _O	Current into any output in the high state (3)	SN74LVTH16245A		64	
I _{IK}	Input clamp current	V _I < 0		-50	mA
I _{OK}	Output clamp current	V _O < 0		-50	mA
		DGG package		70	
		DGV package		58	°C/W
θ_{JA}	Package thermal impedance ⁽⁴⁾	DL package		63	
		GQL/ZQL package		42	
		GRD/ZRD package		36	
T _{stg}	Storage temperature range		-65	150	°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

Recommended Operating Conditions⁽¹⁾

			SN54LVTH	16245A	SN74LVTH1	6245A	UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC}	Supply voltage		2.7	3.6	2.7	3.6	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage			5.5		5.5	V
I _{OH}	High-level output current			-24		-32	mA
I _{OL}	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
$\Delta t/\Delta V_{CC}$	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		– 55	125	-40	85	°C

All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

 ⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 (3) This current flows only when the output is in the high state and V_O > V_{CC}.
 (4) The package thermal impedance is calculated in accordance with JESD 51-7.



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

DAD	AMETED	TEST OF	NUDITIONS	SN54L	VTH16245	4	SN74L	VTH1624	5A	UNIT
PAR	AMETER	IESI CO	ONDITIONS	MIN	TYP ⁽¹⁾	MAX	MIN	TYP ⁽¹⁾	MAX	UNII
V_{IK}		V _{CC} = 2.7 V,	I _I = -18 mA			-1.2			-1.2	V
	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$		$I_{OH} = -100 \ \mu A$	V _{CC} - 0.2			V _{CC} - 0.2			
\/		V _{CC} = 2.7 V,	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V
V _{OH}		V _{CC} = 3 V	I _{OH} = -24 mA	2						V
		v _{CC} = 3 v	$I_{OH} = -32 \text{ mA}$				2			
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2	
	VCC - 2.7 V		I _{OL} = 24 mA			0.5			0.5	
\/			I _{OL} = 16 mA			0.4			0.4	V
V_{OL} $V_{CC} = 3 V$		V - 2 V	I _{OL} = 32 mA			0.5			0.5	V
		$v_{CC} = 3 \text{ V}$	I _{OL} = 48 mA			0.55				
			I _{OL} = 64 mA						0.55	
	Control	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1	
	inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V		10				10	
I _I	_		V _I = 5.5 V	20				20	μΑ	
	A or B port ⁽²⁾	$V_{CC} = 3.6 \text{ V}$	$V_I = V_{CC}$			5			5	
	port		V _I = 0			- 5			- 5	
I _{off}		$V_{CC} = 0$,	V_I or $V_O = 0$ to 4.5 V						±100	μΑ
		V _{CC} = 3 V	V _I = 0.8 V	75			75			
I _{I(hold)}	A or B	v _{CC} = 3 v	V _I = 2 V	-75			-75			μΑ
·I(noid)	port	$V_{CC} = 3.6 \text{ V},^{(3)}$	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						500 -750	μ
I _{OZPU}	1	$\frac{V_{CC}}{OE}$ = 0 to 1.5 V, V_{O} = $\frac{V_{CC}}{OE}$ = don't care	0.5 V to 3 V,		:	±100 ⁽⁴⁾			±100	μΑ
I _{OZPD}		$\frac{V_{CC}}{OE}$ = 1.5 V to 0, V_{O} = $\frac{V_{CC}}{OE}$ = don't care	0.5 V to 3 V,		:	±100 ⁽⁴⁾			±100	μΑ
		V _{CC} = 3.6 V,	Outputs high			0.19			0.19	
I_{CC}	$I_0 = 0$		Outputs low			5			5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			0.19			0.19	
ΔI _{CC} ⁽⁵⁾		V _{CC} = 3 V to 3.6 V, Or Other inputs at V _{CC} or	ne input at V _{CC} – 0.6 V, GND			0.2			0.2	mA
Ci		V _I = 3 V or 0			4			4		pF
C _{io}		V _O = 3 V or 0			10			10		pF

 ⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.
 (2) Unused pins at V_{CC} or GND
 (3) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

 ⁽⁴⁾ On products compliant to MIL-PRF-38535, this parameter is not production tested.
 (5) This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

SN54LVTH16245A, SN74LVTH16245A 3.3-V ABT 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS143R-MAY 1992-REVISED NOVEMBER 2006



Switching Characteristics

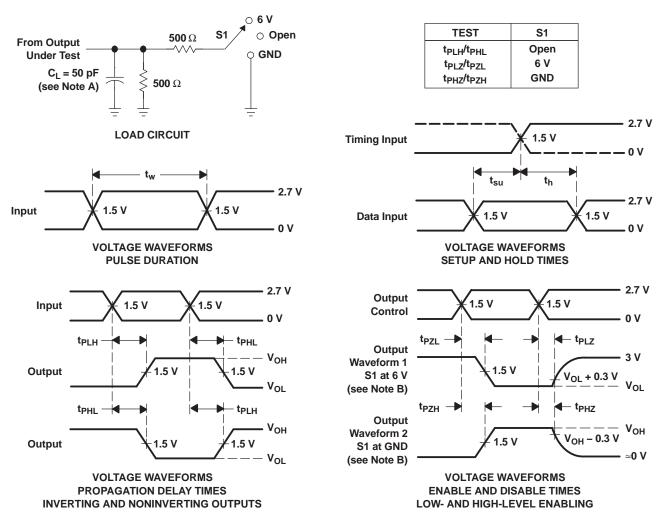
over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SNS	4LVTH	16245	4		SN74L	VTH16	245A		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 3.3 V \pm 0.3 V		V _{CC} = 2.7 V		V_{CC} = 3.3 V \pm 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP ⁽¹⁾	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	0.5	4.5		4.6	1.5	2.3	3.3		3.7	no
t _{PHL}	AUID	BUIA	0.5	4.4		3.9	1.3	2.1	3.3		3.5	ns
t _{PZH}	ŌĒ	A or B	0.5	6.5		6.6	1.5	2.8	4.5		5.3	ns
t _{PZL}	OE	AOIB	0.5	5.4		6.2	1.6	2.9	4.6		5.2	115
t _{PHZ}	ŌĒ	A or B	1	6.8		7	2.3	3.7	5.1		5.5	20
t _{PLZ}	OE	AUID	1	6.2		6.3	2.2	3.5	5.1		5.4	ns
t _{sk(LH)}									0.5		0.5	20
t _{sk(HL)}									0.5		0.5	ns

⁽¹⁾ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 Ω , $t_{f} \leq$ 2.5 ns, $t_{f} \leq$ 2.5 ns.
- D. The outputs are measured one at a time, with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





6-Feb-2020

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9668601QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9668601QX A SNJ54LVTH16245 AWD	Samples
5962-9668601VXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9668601VX A SNV54LVTH16245 AWD	Samples
74LVTH16245ADGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADGGRG4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADGVRG4	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
74LVTH16245ADLG4	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
74LVTH16245ADLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADGVR	ACTIVE	TVSOP	DGV	48	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LL245A	Samples
SN74LVTH16245ADL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245ADLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH16245A	Samples
SN74LVTH16245AZQLR	LIFEBUY	BGA MICROSTAR JUNIOR	ZQL	56	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LL245A	
SN74LVTH16245AZRDR	LIFEBUY	BGA MICROSTAR JUNIOR	ZRD	54	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-1-260C-UNLIM	-40 to 85	LL245A	
SNJ54LVTH16245AWD	ACTIVE	CFP	WD	48	1	TBD	Call TI	N / A for Pkg Type	-55 to 125	5962-9668601QX A SNJ54LVTH16245	Samples



PACKAGE OPTION ADDENDUM

6-Feb-2020

Orderable Device	Status	Package Type Packag	_	e Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)	Drawin	g Qty	(2)	(6)	(3)		(4/5)	
								AWD	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54LVTH16245A, SN54LVTH16245A-SP, SN74LVTH16245A:

Catalog: SN74LVTH16245A, SN54LVTH16245A



PACKAGE OPTION ADDENDUM

6-Feb-2020

Automotive: SN74LVTH16245A-Q1, SN74LVTH16245A-Q1

● Enhanced Product: SN74LVTH16245A-EP, SN74LVTH16245A-EP

• Military: SN54LVTH16245A

● Space: SN54LVTH16245A-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 12-Feb-2019

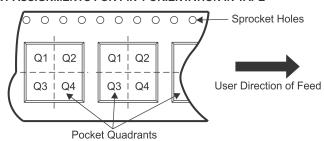
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH16245ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1
SN74LVTH16245ADGVR	TVSOP	DGV	48	2000	330.0	16.4	7.1	10.2	1.6	12.0	16.0	Q1
SN74LVTH16245ADLR	SSOP	DL	48	1000	330.0	32.4	11.35	16.2	3.1	16.0	32.0	Q1
SN74LVTH16245AZQLR	BGA MI CROSTA R JUNI OR	ZQL	56	1000	330.0	16.4	4.8	7.3	1.5	8.0	16.0	Q1
SN74LVTH16245AZRDR	BGA MI CROSTA R JUNI OR	ZRD	54	1000	330.0	16.4	5.8	8.3	1.55	8.0	16.0	Q1

www.ti.com 12-Feb-2019



*All dimensions are nominal

All differsions are norminal									
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)		
SN74LVTH16245ADGGR	TSSOP	DGG	48	2000	367.0	367.0	45.0		
SN74LVTH16245ADGVR	TVSOP	DGV	48	2000	367.0	367.0	38.0		
SN74LVTH16245ADLR	SSOP	DL	48	1000	367.0	367.0	55.0		
SN74LVTH16245AZQLR	BGA MICROSTAR JUNIOR	ZQL	56	1000	350.0	350.0	43.0		
SN74LVTH16245AZRDR	BGA MICROSTAR JUNIOR	ZRD	54	1000	350.0	350.0	43.0		

DL (R-PDSO-G48)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

PowerPAD is a trademark of Texas Instruments.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153



PLASTIC BALL GRID ARRAY



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.
- 3. No metal in this area, indicates orientation.



PLASTIC BALL GRID ARRAY



NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For information, see Texas Instruments literature number SPRAA99 (www.ti.com/lit/spraa99).



PLASTIC BALL GRID ARRAY



NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

ZRD (R-PBGA-N54)

PLASTIC BALL GRID ARRAY



 $\hbox{NOTES:} \quad \hbox{A. All linear dimensions are in millimeters.}$

- B. This drawing is subject to change without notice.
- Falls within JEDEC MO-205 variation DD.
- D. This package is lead-free. Refer to the 54 GRD package (drawing 4204759) for tin-lead (SnPb).



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